

Issue	Cover Story	Trend & Analysis				Design & Technology			
		Technology Trends	Opinions	Interview	China Fabless	Design Corner	Test & Measurement	New Products	Hardware Innovation
<b>January</b> Booking deadline: Nov. 20	New year outlook	•	•	•	•	- EMI/EMC - Circuit Protection - Radar Technology	Network Analyzer	•	
<b>February</b> Booking deadline: Dec. 21	Power management technology under the requirements of carbon neutrality and emission peak	•	•	•	•	- Motor Control - RF/Microwave - Servo Control	Oscilloscope	•	•
<b>March</b> Booking deadline: Jan. 18	Software-defined new automotive architecture	•	•	•	•	- Human-Machine Interaction - Touch Technology - Speech Recognition / Processing	Test Software /IP	•	•
<b>April</b> Booking deadline: Feb. 19	The breakthrough of domestic EDA	•	•	•	•	- 5G Communication - Wireless Connection - Video Surveillance	Microwave RF Test	•	
<b>May</b> Booking deadline: Mar. 19	New trend of 5G construction: Stand alone	•	•	•	•	- PCB Design - High Frequency Design - Embedded Design	Power Integrity Measurement	•	•
<b>June</b> Booking deadline: Apr. 20	MCU design based on Arm and RISC-V core	•	•	•	•	- Wearable Gadget Design - Energy Acquisition - Digital Signal Processing	Vector Signal Analysis	•	
<b>July</b> Booking deadline: May 20	Wide bandgap power devices in new energy vehicles	•	•	•	•	- Smart Grid - Wireless Communication - Analog Circuit Design	Spectrum Analyzer	•	•
<b>August</b> Booking deadline: June 21	New "Moore's Law"—Heterogeneous Integration	•	•	•	•	- Mixed Signal Circuit Design - Data Security and Encryption - MCU	EMI Test	•	
<b>September</b> Booking deadline: July 20	The mystery of the mobile phone manufacturer's independent R&D on ISP	•	•	•	•	- Medical Electronics - ADC/DAC - Edge Computing	Impedance Measurement	•	•
<b>October</b> Booking deadline: Aug. 20	Portable device multiple wireless technology test	•	•	•	•	- Power Device - Low Power Design - Digital Power	Mixed Signal Measurement	•	
<b>November</b> Booking deadline: Sept. 17	The "5" era of storage (DDR5, PCIe 5.0)	•	•	•	•	- Audio Design - FPGA/DSP - Wafer Foundry	Signal Integrity Measurement	•	•
<b>December</b> Booking deadline: Oct. 20	Artificial Intelligence and Advanced Manufacturing	•	•	•	•	- LED Lighting - Photoelectric and Display - MEMS Sensor	Embedded System Test	•	

\* For China edition only

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**Note:** The publisher retains the right to reschedule any topic in the calendar.